

**BHCL 453232 summary material content, BI Technologies Corporation**

Index	Item	Material Name	Element Composition	CAS No	Material Mass (mg)	Composition (mg)
1	CORE	Ferrite	Fe <sub>2</sub> O <sub>3</sub>	1309-37-1	25.00	14.750
			NiO	1313-99-1		3.000
			CuO	1317-38-0		2.250
			ZnO	1314-13-2		5.000
2	BODY	Epoxy	Fused Silica	60676-86-0	68.00	44.880
			Epoxy Resin	29690-82-2		12.920
			Phenol Resin	9003-35-4		6.120
			Metal Hydroxide	21645-51-2		4.080
3	WIRE	UEW Wire	Copper	7440-50-8	19.00	17.480
			Polyester Resin	65086-73-9		1.520
4	SOLDER	Lead free solder	Sn	7440-31-5	2.00	1.920
			Ag	7440-22-4		0.080
5	TERMINAL	Tin Plated Copper Wire	Copper	7440-50-8	9.50	9.405
			Tin	7440-31-5		0.095

Total Weight	123.50
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